

Description

These N-Channel enhancement mode power field effect transistors are using SGT technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

General Features

V_{DS}	100V
I_D (at $V_{GS}=10V$)	70A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	8.5m Ω (Typ)

Application

- Battery protection
- Load switch
- Uninterruptible power supply

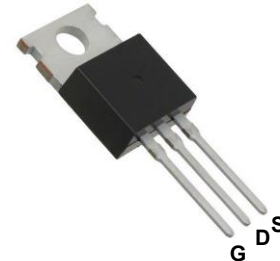
Package Marking and Ordering Information

Device	Device Marking	Device Package	Reel Size	Tape width	Quantity
LMFB70N10	HC1010	TO-220	-	-	1000 units

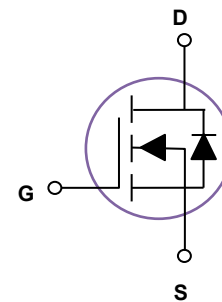
Absolute Maximum Ratings (TC=25°C unless otherwise noted)

Parameter	Symbol	Maximum	Units	
Drain-Source Voltage	V_{DS}	100	V	
Gate-Source Voltage	V_{GS}	± 20	V	
Drain Current-Continuous	TC=25°C	I_D	70	
	TC=100°C	I_D	44	
Maximum Power Dissipation	P_D	122	W	
Single pulse avalanche energy ⁽¹⁾	E_{AS}	230	mJ	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C	
Thermal Characteristics				
Parameter	Symbol	Typ	Max	Unit
Thermal Resistance junction-case	$R_{\theta JC}$		1.02	°C /W
Thermal Resistance junction-to-Ambient	$R_{\theta JA}$		62	°C /W

Dimensions TO-220



Pin Configuration



Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	100			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =100V, V _{GS} =0V			1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =+20V, V _{DS} =0V			100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.2	1.6	2.5	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =20A		8.5	10.5	mΩ
		V _{GS} =4.5V, I _D =15A		11	15	mΩ
DYNAMIC PARAMETERS						
C _{ISS}	Input Capacitance	V _{DS} =50V, V _{GS} =0V, F=1.0MHz		1450		pF
C _{OSS}	Output Capacitance			215		pF
C _{RSS}	Reverse Transfer Capacitance			8		pF
SWITCHING PARAMETERS						
t _{d(on)}	Turn-on Delay Time	V _{DD} =50V, I _b =1A, V _{GS} =10V, R _G =6Ω		14		nS
t _r	Turn-on Rise Time			20.8		nS
t _{d(off)}	Turn-Off Delay Time			42		nS
t _f	Turn-Off Fall Time			30		nS
Q _g	Total Gate Charge	V _{DS} =50V, I _D =10A, V _{GS} =10V		26		nC
Q _{gs}	Gate-Source Charge			6.5		nC
Q _{gd}	Gate-Drain Charge			5.3		nC
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz		1.04		Ω
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _{SD} =1A		0.7	1.2	V

Note:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=50V, V_{GS}=10V, L=0.5mH, I_{AS}=48A, Starting T_J=25°C
3. The data tested by pulsed, pulse width ≅ 300us, duty cycle ≅ 2%.
4. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristics

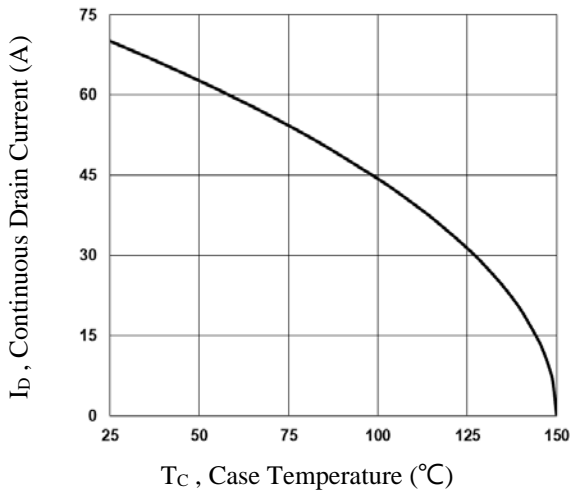


Fig.1 Continuous Drain Current vs. T_C

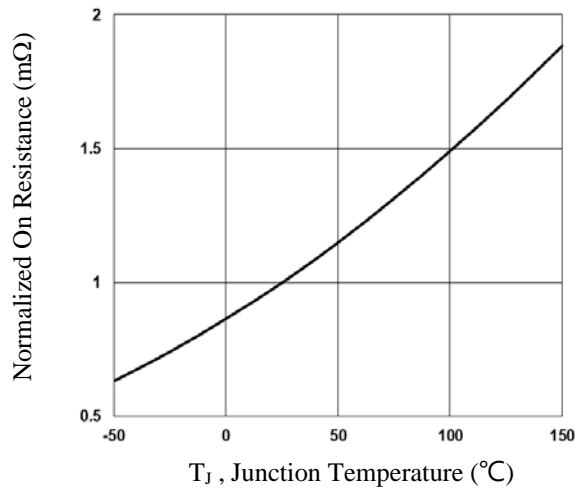


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

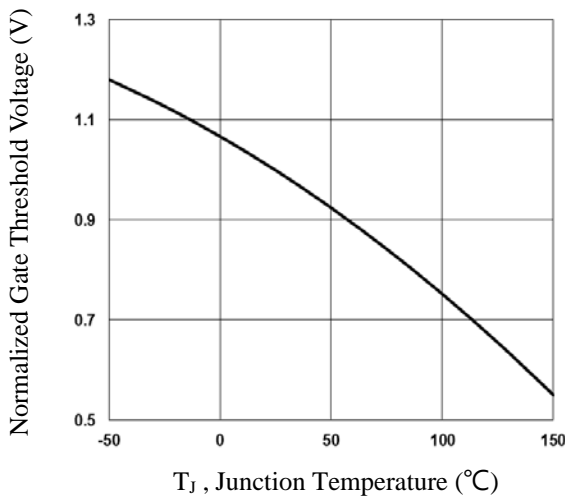


Fig.3 Normalized V_{th} vs. T_J

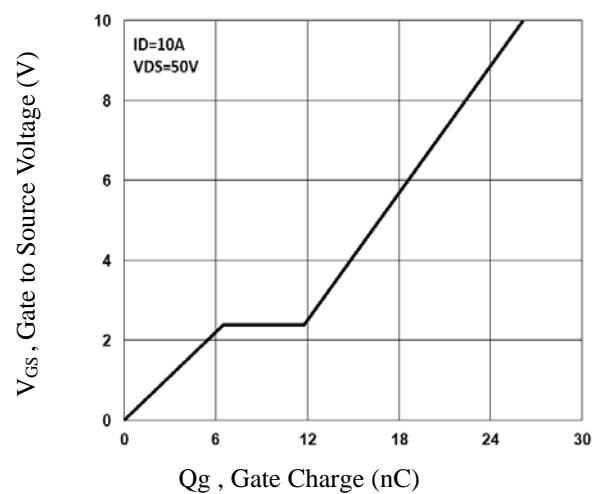


Fig.4 Gate Charge Characteristics

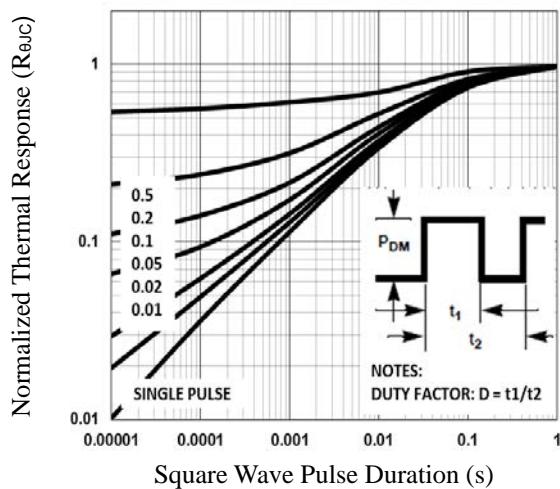


Fig.5 Normalized Transient Impedance

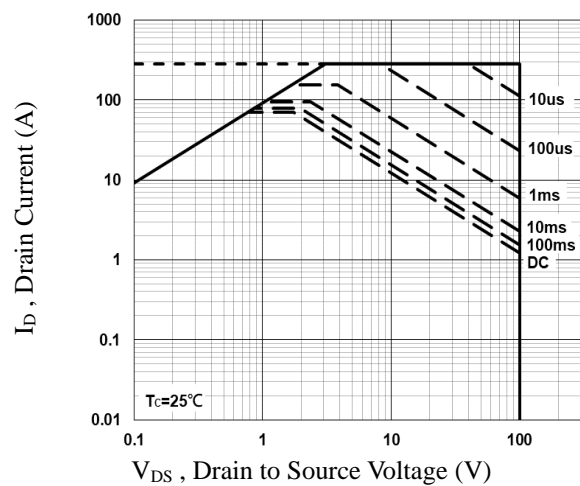


Fig.6 Maximum Safe Operation Area

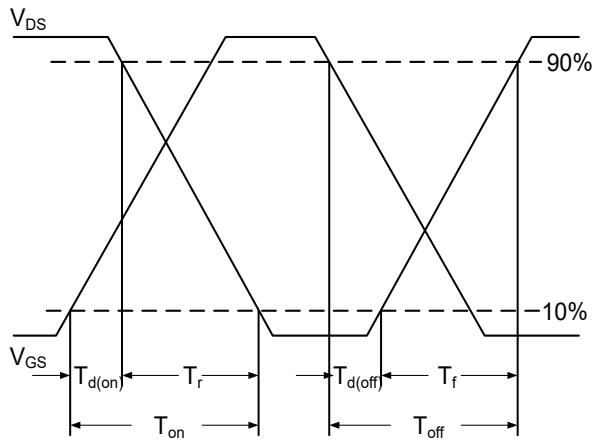


Fig.7 Switching Time Waveform

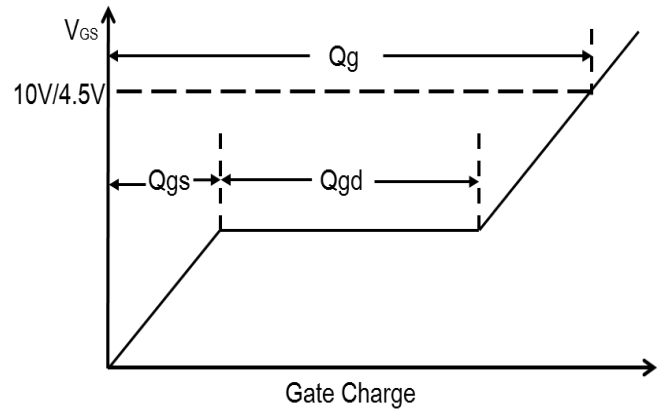
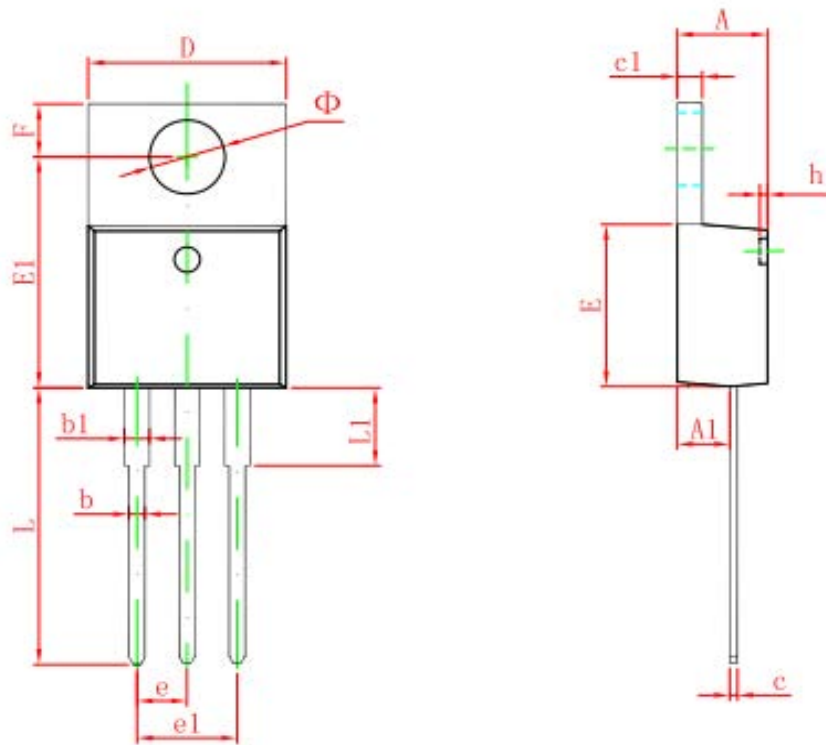


Fig.8 Gate Charge Waveform

TO-220 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.470	4.670	0.176	0.184
A1	2.520	2.820	0.099	0.111
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
E	8.500	8.900	0.335	0.350
E1	12.060	12.460	0.475	0.491
e	2.540 TYP		0.100 TYP	
e1	4.980	5.180	0.196	0.204
F	2.590	2.890	0.102	0.114
h	0.000	0.300	0.000	0.012
L	13.400	13.800	0.528	0.543
L1	3.560	3.960	0.140	0.156
Φ	3.735	3.935	0.147	0.155

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